

DATASHEET

Technical Data Sheet High Power Infrared LED

EAIST3535A0



Features

- Small package with high efficiency
- Peak wavelength $\lambda p=855nm$
- Soldering methods:SMT
- Thermal resistance (junction to lead): 11°C/W.
- Pb free
- The product itself will remain within RoHS compliant version.

Descriptions

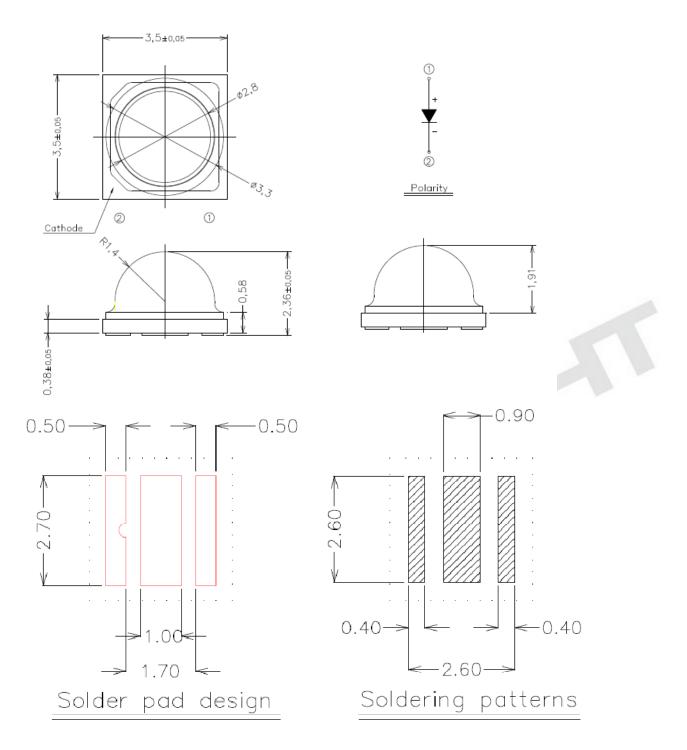
- EAIST3535A0 series is an infrared emitting diode in miniature SMD package which is molded in a water clear silicone with spherical top view lens.
- The device is spectrally matched with silicon photodiode, Phototransistor.

Applications

- CCD Camera
- Infrared applied system



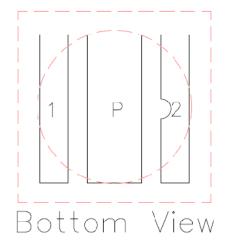
Package Dimensions

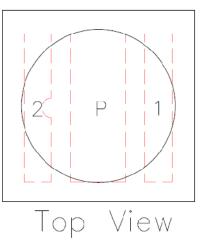


- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are ± 0.1 mm.
- 3. Do not handle the device by the lens. Incorrect force applied to the lens may lead to the failure of devices.



Pad Configuration





PAD	FUNCTION
1	ANODE
2	CATHODE
Р	THERMAL PAD

Absolute Maximum Ratings (Ta=25°C)

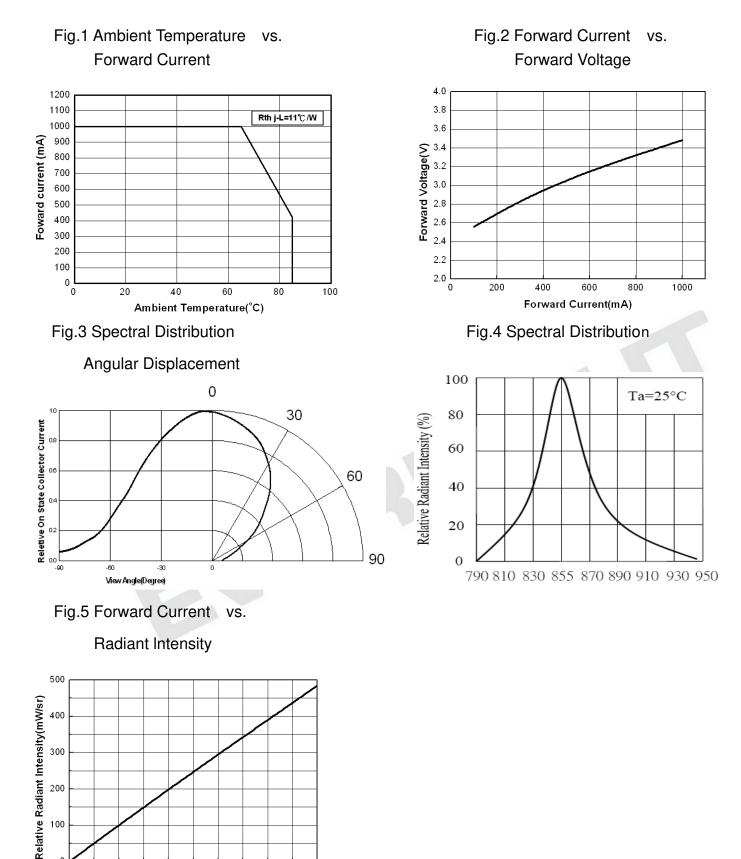
Parameter	Symbol	Rating	Unit
Forward Current	$\mathrm{I_{F}}$	1	А
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Junction temperature	Tj	115	°C
Thermal resistance (junction to leadframe)	R _{th(j-L)}	11	°C/W
Power Dissipation @I _F =1000mA	P _d	3.7	W

Note: We suggest that customer should add the heat sink with EAIST3535A0 to exclude the heat.

Electro-Optical Characteristics (Ta=25°C)

IF=1A 1030 IF=350mA 150 170	Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$			IF=350mA		350		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Total Radiated Power	Ро	IF=700mA		700		mW
Radiant Intensity I _E IF=700mA 330 350 mW/st IF=1A 450 470 mW/st Peak Wavelength λp IF=350mA 855 nm Spectral Bandwidth $\Delta \lambda$ IF=350mA 25 nm Spectral Bandwidth $\Delta \lambda$ IF=350mA 3.1 Nm Forward Voltage V_F IF=700mA 3.4 V IF=1A 3.7 V V Reverse Current I _R VR=5V 10 µA			IF=1A		1030		
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$			IF=350mA	150	170		mW/sr
Peak Wavelength λp IF=350mA 855 nm Spectral Bandwidth $\Delta\lambda$ IF=350mA 25 nm Spectral Bandwidth $\Delta\lambda$ IF=350mA 3.1 nm Forward Voltage V_F IF=700mA 3.4 V IF=1A 3.7 V IA Reverse Current I_R VR=5V 10 µA	Radiant Intensity	I_{E}	IF=700mA	330	350		
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			IF=1A	450	470		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Peak Wavelength	λp	IF=350mA		855		nm
Forward Voltage V_F IF=700mA 3.4 V IF=1A 3.7 V Reverse Current I _R VR=5V 10 μA	Spectral Bandwidth	Δλ	IF=350mA		25		nm
$\begin{array}{c c c c c c c c c c c c c c c c c c c $			IF=350mA		3.1		V
Reverse Current I_R VR=5V10 μA	Forward Voltage	\mathbf{V}_{F}	IF=700mA		3.4		
			IF=1A		3.7	-	
View Angle 201/2 IF=20mA 90 deg	Reverse Current	I _R	VR=5V			10	μA
	View Angle	201/2	IF=20mA		90	-	deg

Typical Electro-Optical Characteristics Curves



900 1000

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Forward Current(mA)

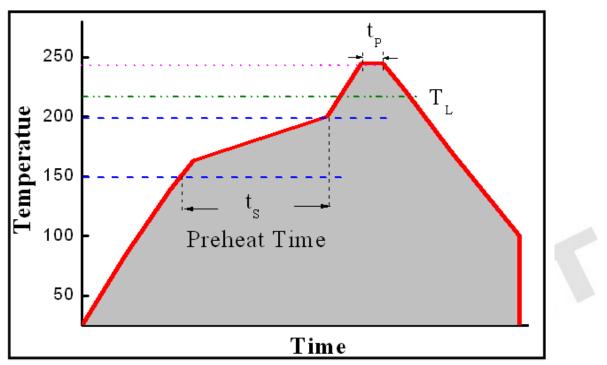
0 100 200 300 400 500 600 700 800

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Reflow Soldering Characteristics

For Reflow Process

- 1. EAIST3535A0 is suitable for SMT processes.
- 2. Curing of glue in oven must be according to standard operation flow processes.



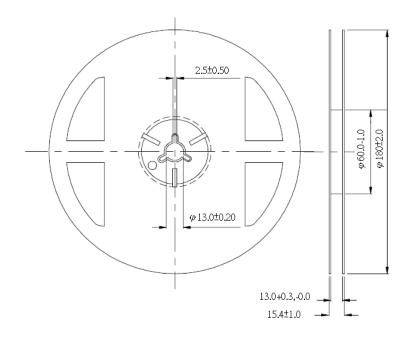
Profile Feature	Lead Free Assembly		
Ramp-Up Rate	2-3 °C/S		
Preheat Temperature	150-200 ℃		
Preheat Time (t _s)	60-120 S		
Liquid Temperature (T _L)	217 °C		
Time maintained above T_L	60-90 S		
Peak Temperature (T _P)	240±5 ℃		
Peak Time (t _P)	Max 20 S		
Ramp-Down Rate	3-5 ℃/S		

3. Reflow soldering should not be done more than twice.

4. In soldering process, stress on the LEDs during heating should be avoided.



Package Dimensions

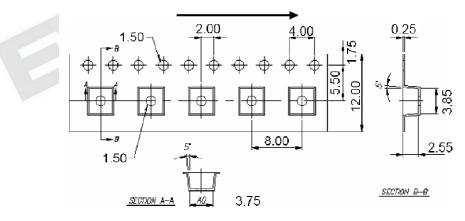


Note: 1. Dimensions are in millimeters

2. The tolerances unless mentioned is ±0.1mm

Carrier Tape Dimensions: Loaded quantity 400 PCS per reel.

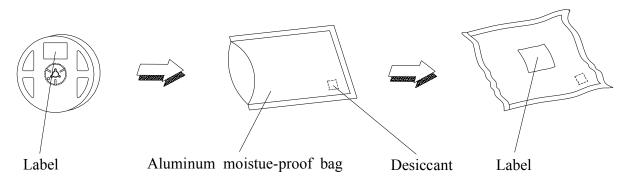
Feed Direction



Note: 1. Dimensions are in millimeters

2. The tolerances unless mentioned is ±0.1mm

Moisture Resistant Packaging



Label Form Specification



CPN: Customer's Production Number P/N : Production Number QTY: Packing Quantity CAT: Ranks HUE: Peak Wavelength REF: Reference LOT No: Lot Number MADE IN TAIWAN: Production Place

Notes

- 1. Above specification may be changed without notice. Everlight Americas will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. Everlight Americas assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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